

SOT1330-1

plastic small outline package; 14 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO14
Package type industry code	SO14
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-7-2012

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		8.55	-	8.65	8.75	mm
E	package width		3.8	-	3.9	4	mm
A	seated height		-	-	-	1.75	mm
A ₂	package height		1.4	-	1.47	1.55	mm
e	nominal pitch		-	-	1.27	-	mm
n ₂	actual quantity of termination		-	-	14	-	



2. Package outline

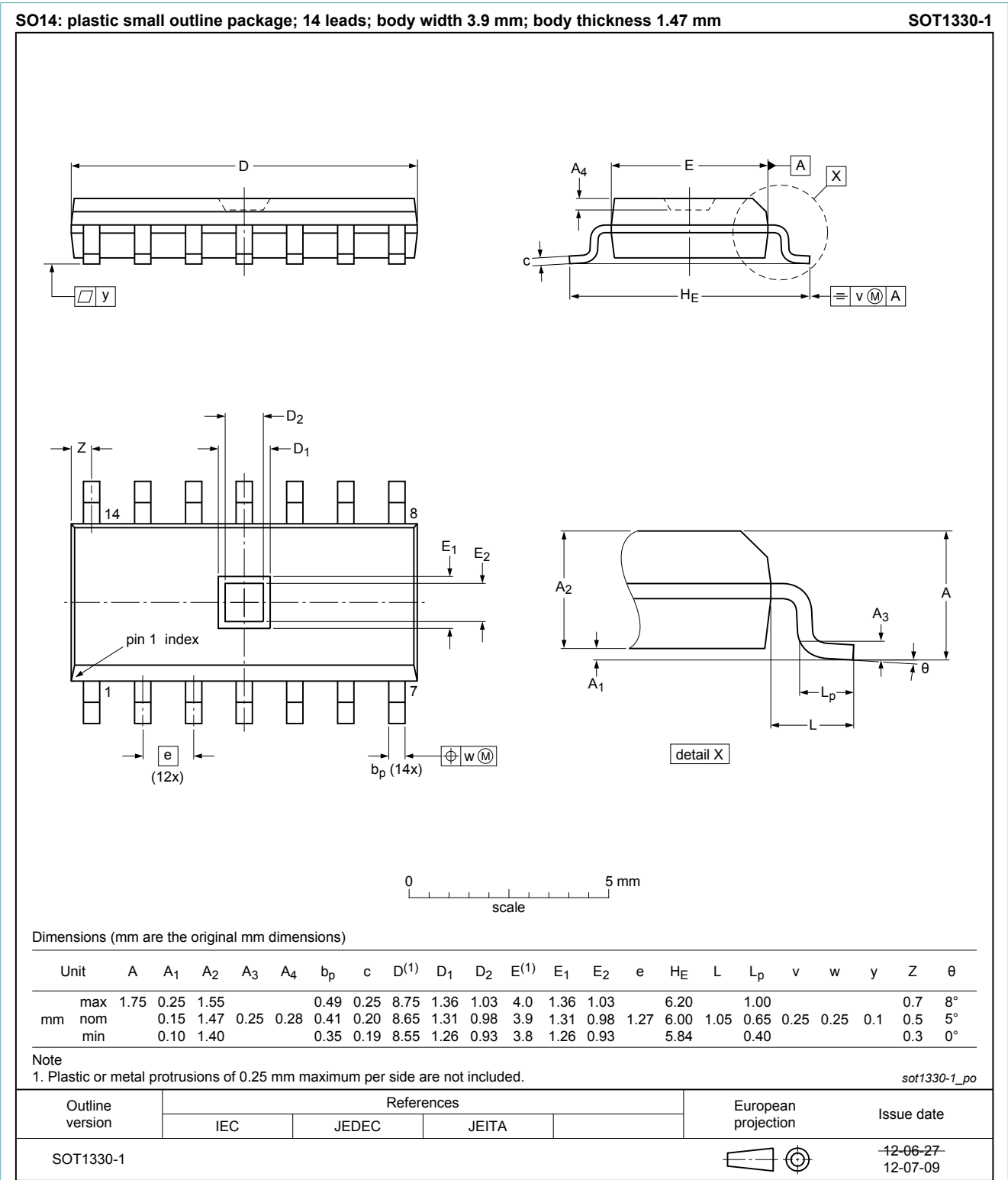


Fig. 1. Package outline SO14 (SOT1330-1)

3. Legal information

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Date of release: 8 February 2016